

General Description

This planar stripe MOSFET has better characteristics, such as fast switching time, low on resistance, fast reverse recovery time, low gate charge and excellent avalanche characteristics. It is mainly suitable for active power factor correction and switching mode power supplies.

FEATURES

- $V_{DSS}=600V$, $I_D=10A$
- Drain-Source ON Resistance :
 $R_{DS(ON)}(\text{Max})=0.69 \Omega$ @ $V_{GS}=10V$
- $Q_g(\text{typ.})=29.5nC$
- $t_{rr}(\text{typ.})=150\text{nS}$

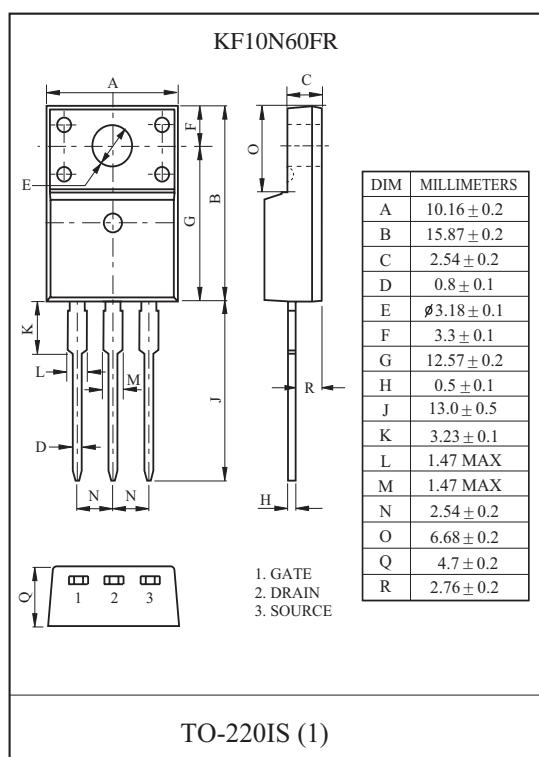
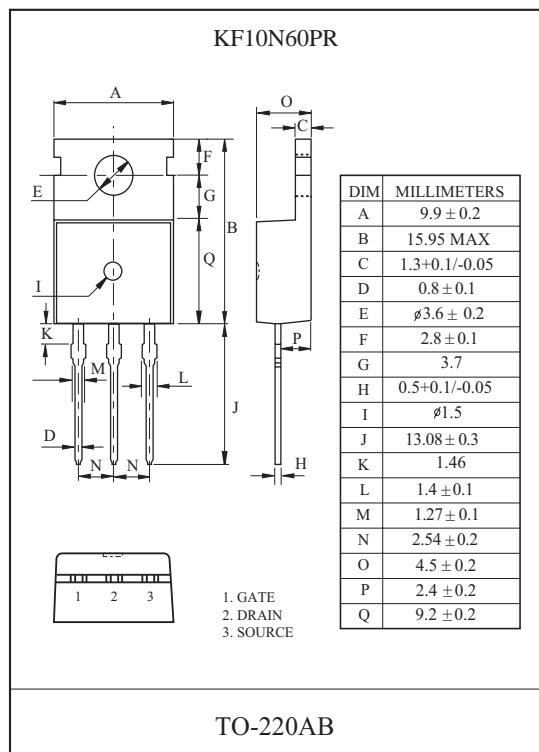
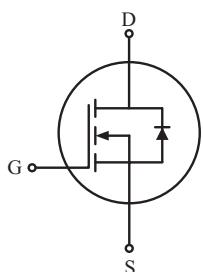
MAXIMUM RATING (Tc=25 °C)

CHARACTERISTIC	SYMBOL	RATING		UNIT
		KF10N60PR	KF10N60FR	
Drain-Source Voltage	V_{DSS}	600		V
Gate-Source Voltage	V_{GSS}	± 30		V
Drain Current	I_D @ $T_C=25^\circ\text{C}$	10	10*	A
	I_D @ $T_C=100^\circ\text{C}$	6	6*	
	I_{DP} Pulsed (Note1)	25	25*	
Single Pulsed Avalanche Energy (Note 2)	E_{AS}	400		mJ
Repetitive Avalanche Energy (Note 1)	E_{AR}	16.5		mJ
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns
Drain Power Dissipation	P_D Tc=25 °C	190	50	W
	Derate above 25 °C	1.52	0.4	W/ °C
Maximum Junction Temperature	T_j	150		°C
Storage Temperature Range	T_{stg}	-55 ~ 150		°C
Thermal Characteristics				
Thermal Resistance, Junction-to-Case	R_{thJC}	0.65	2.5	°C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62.5	62.5	°C/W

* : Drain current limited by maximum junction temperature.

PIN CONNECTION

(KF10N60PR, KF10N60FR)



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ELECTRICAL CHARACTERISTICS (Tc=25 °C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250 μA, V _{GS} =0V	600	-	-	V
Breakdown Voltage Temperature Coefficient	ΔBV _{DSS} /ΔT _j	I _D =250 μA, Referenced to 25 °C	-	0.6	-	V/ °C
Drain Cut-off Current	I _{DSS}	V _{DS} =600V, V _{GS} =0V	-	-	10	μA
Gate Threshold Voltage	V _{th}	V _{DS} =V _{GS} , I _D =250 μA	2	-	4	V
Gate Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	-	-	±100	nA
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5A	-	0.59	0.69	Ω
Dynamic						
Total Gate Charge	Q _g	V _{DS} =480V, I _D =10A V _{GS} =10V (Note4,5)	-	29.5	-	nC
Gate-Source Charge	Q _{gs}		-	6.5	-	
Gate-Drain Charge	Q _{gd}		-	12.5	-	
Turn-on Delay time	t _{d(on)}	V _{DD} =300V I _D =10A R _G =25 Ω (Note4,5)	-	32	-	ns
Turn-on Rise time	t _r		-	35	-	
Turn-off Delay time	t _{d(off)}		-	88	-	
Turn-off Fall time	t _f		-	30.5	-	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	1255	-	pF
Output Capacitance	C _{oss}		-	160	-	
Reverse Transfer Capacitance	C _{rss}		-	16.5	-	
Source-Drain Diode Ratings						
Continuous Source Current	I _S	V _{GS} <V _{th}	-	-	10	A
Pulsed Source Current	I _{SP}		-	-	40	
Diode Forward Voltage	V _{SD}	I _S =10A, V _{GS} =0V	-	-	1.4	V
Reverse Recovery Time	t _{rr}	I _S =10A, V _{GS} =0V, dI _S /dt=100A/μs	-	150	-	ns
Reverse Recovery Charge	Q _{rr}		-	1.0	-	μC

Note 1) Repetitive rating : Pulse width limited by junction temperature.

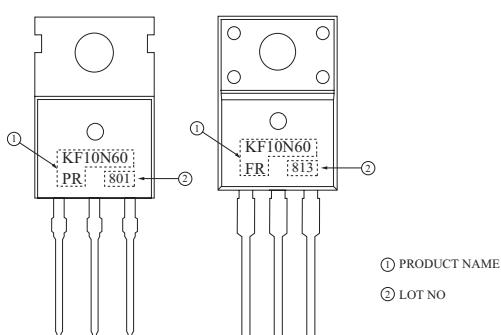
Note 2) L = 7.3mH, I_S=10A, V_{DD}=50V, R_G=25 Ω, Starting T_j=25 °C.

Note 3) I_S≤10A, dI/dt≤200A/μs, V_{DD}≤BV_{DSS}, Starting T_j=25 °C.

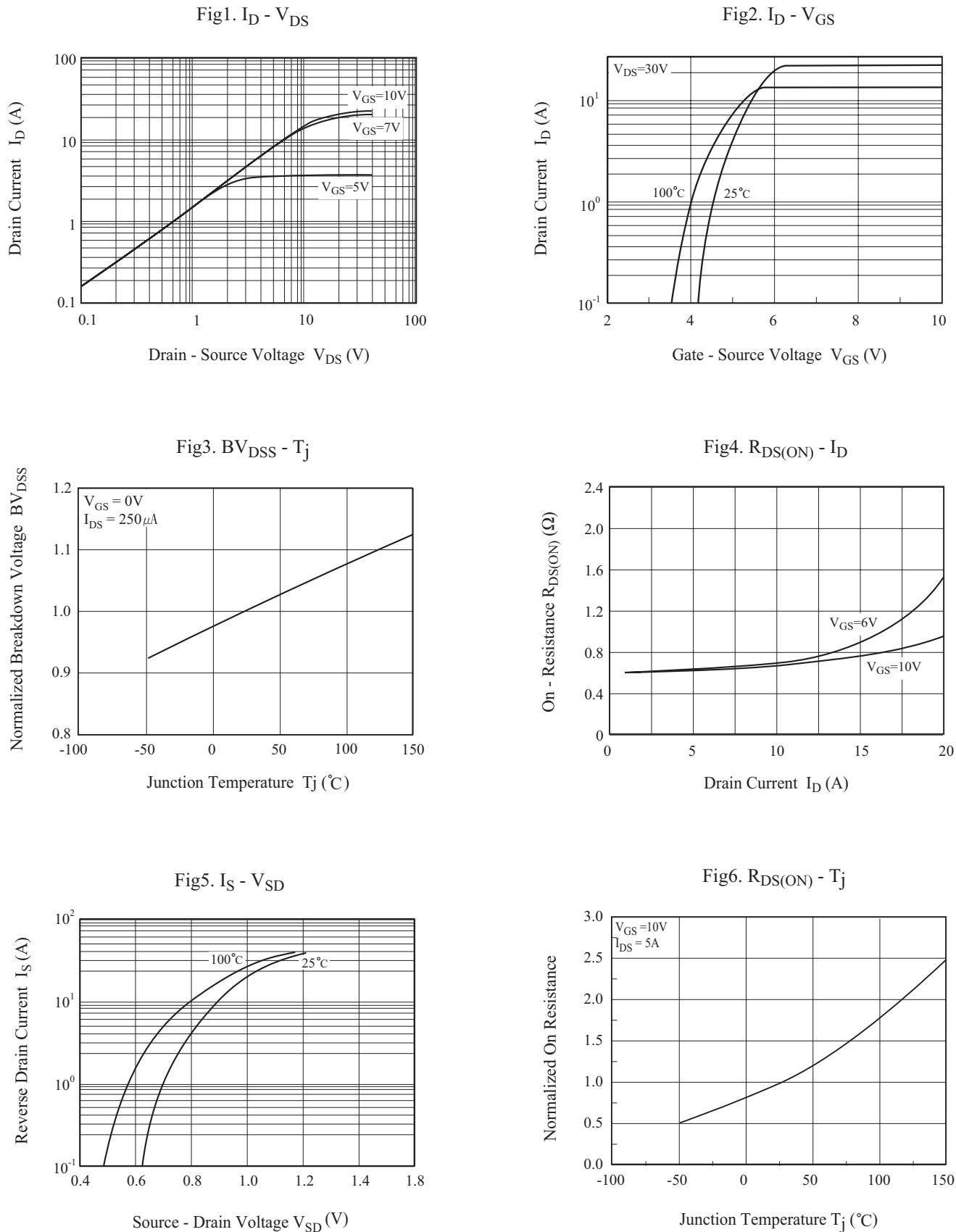
Note 4) Pulse Test : Pulse width ≤ 300 μs, Duty Cycle ≤ 2%.

Note 5) Essentially independent of operating temperature.

Marking



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Fig 7. C - V_{DS}

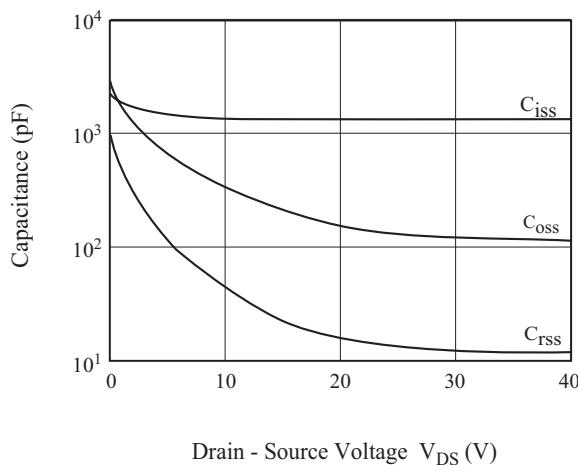


Fig8. Q_g- V_{GS}

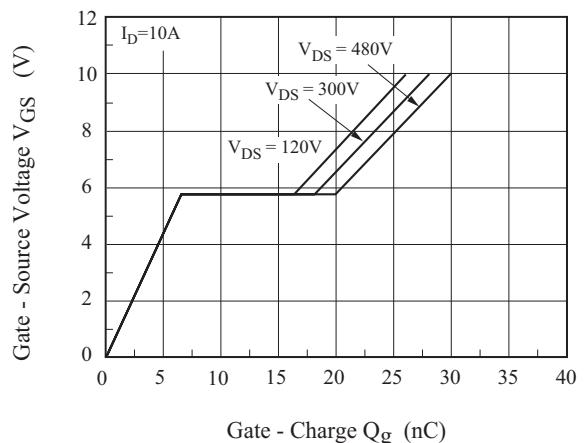


Fig9. Safe Operation Area

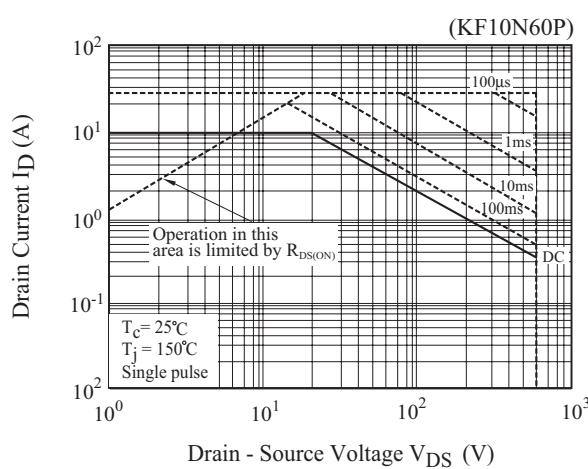


Fig10. Safe Operation Area

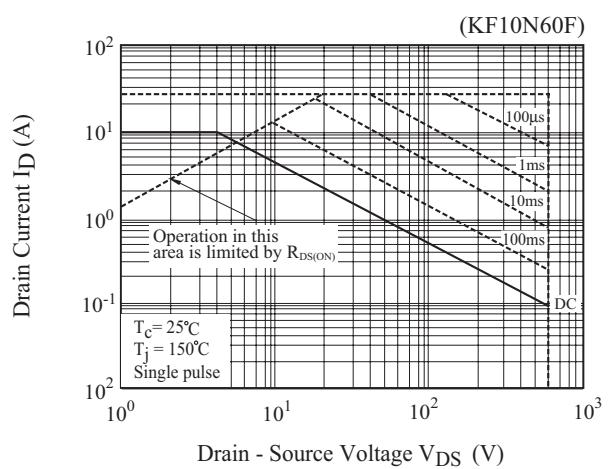
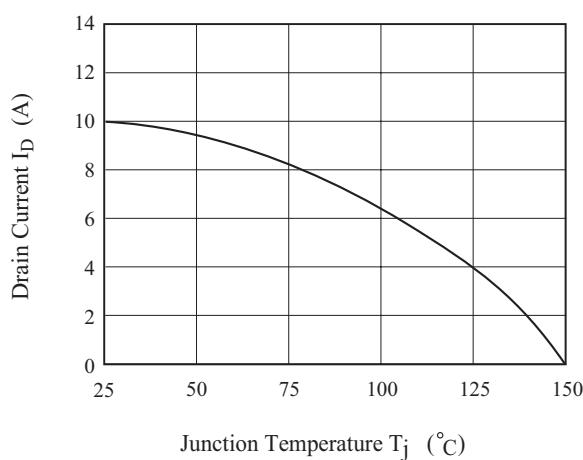


Fig11. I_D - T_j



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Fig12. Transient Thermal Response Curve

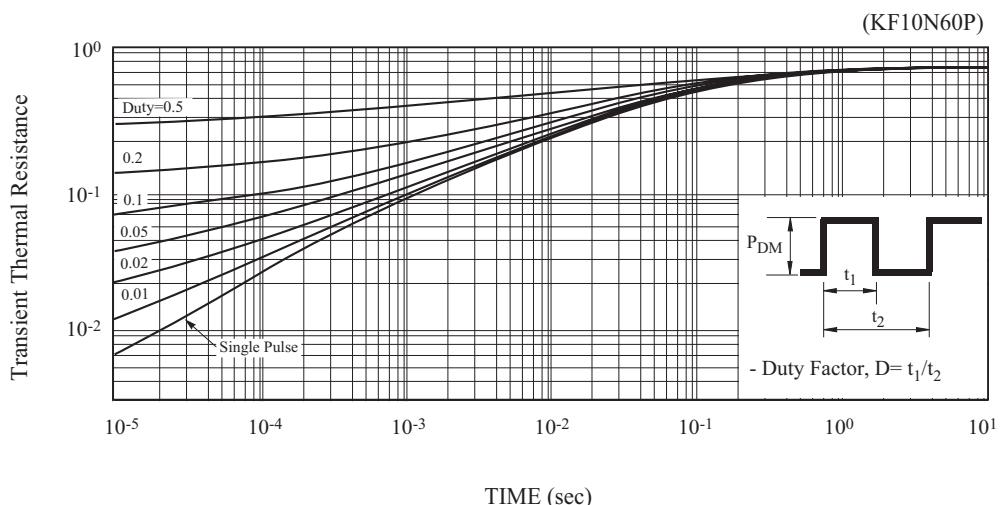
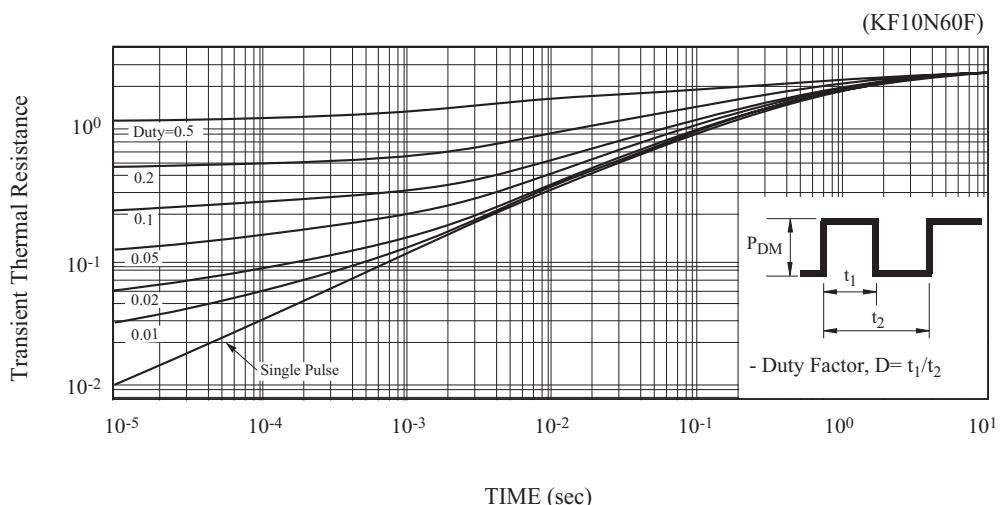


Fig13. Transient Thermal Response Curve



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Fig14. Gate Charge

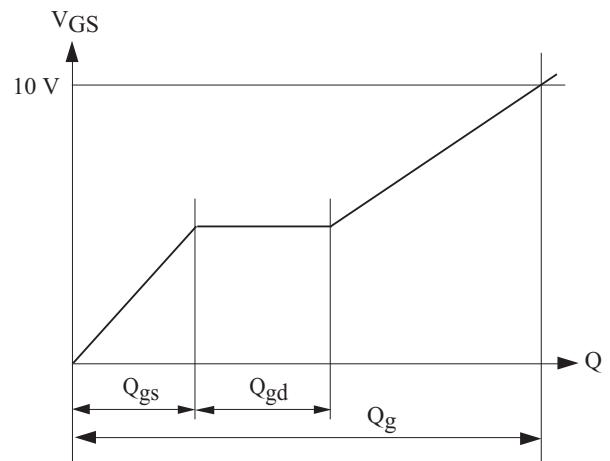
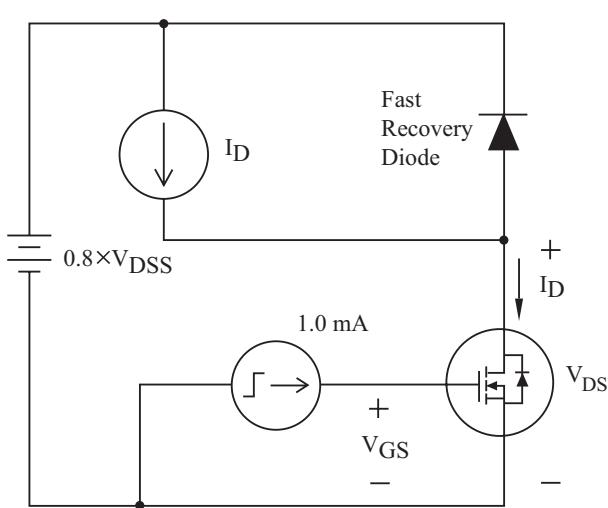
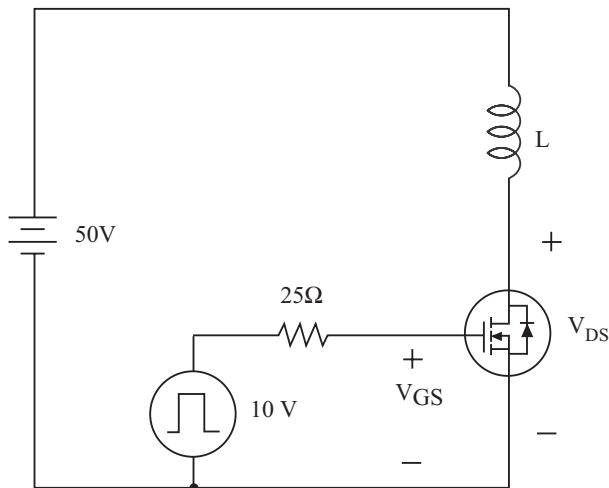


Fig15. Single Pulsed Avalanche Energy



$$E_{AS} = \frac{1}{2} L I_{AS}^2 \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

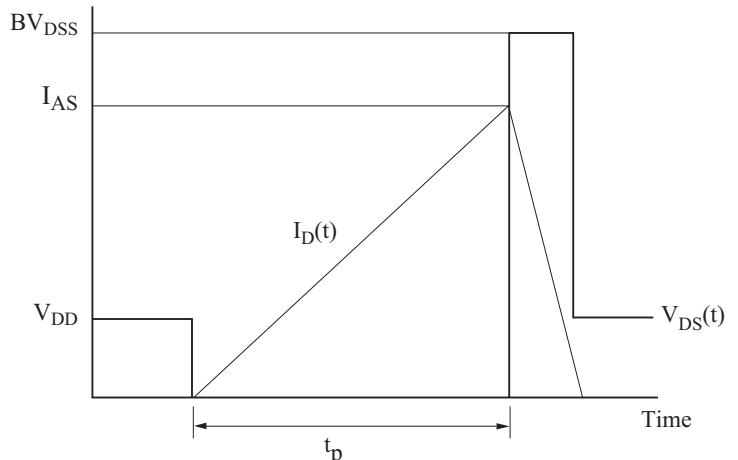
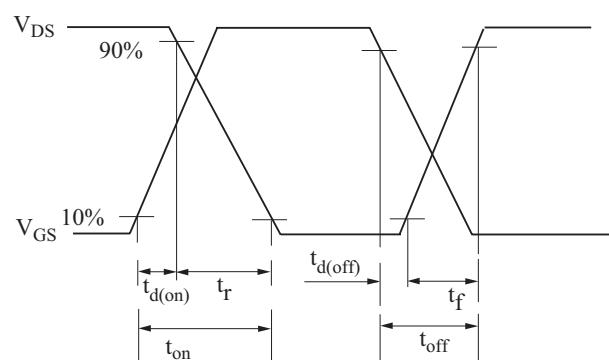
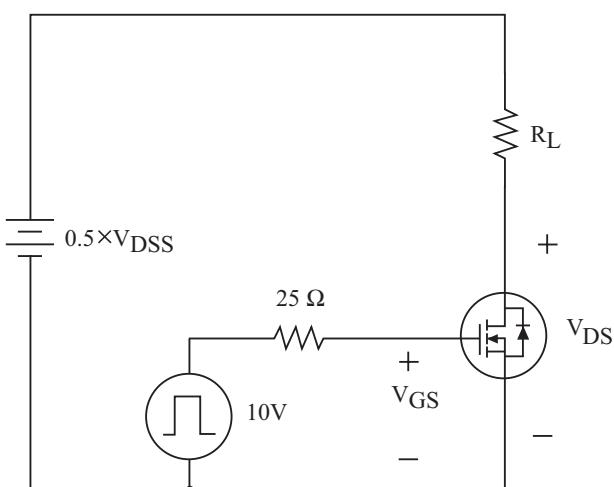


Fig16. Resistive Load Switching



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Fig17. Source - Drain Diode Reverse Recovery and dv / dt

